

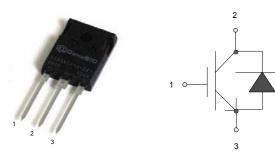
IGBT/SiC Diode Co-pack

GA35XCP12-247

V _{CES}	=	1200 V
I _{см}	=	35 A
$V_{CE(SAT)}$	=	3.0 V

Features

- Optimal Punch Through (OPT) technology
- SiC freewheeling diode
- · Positive temperature coefficient for easy paralleling
- Extremely fast switching speeds
- Temperature independent switching behavior of SiC rectifier
- Best RBSOA/SCSOA capability in the industry
- High junction temperature
- Industry standard packaging



TO – 247AB

Advantages

- Industry's highest switching speeds
- High temperature operation
- Improved circuit efficiency
- Low switching losses

Applications

Package

RoHS Compliant

- Solar Inverters
- Aerospace Actuators
- Server Power Supplies
- Resonant Inverters > 100 kHz
- Inductive Heating
- Electronic Welders

Maximum Ratings, at T_i = 150 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
IGBT				
Collector-Emitter Voltage	V _{CES}		1200	V
DC-Collector Current	I _{CM}	T _c ≤ 105 °C	35	А
Gate Emitter Peak Voltage	V _{GES}		± 20	V
Operating Temperature	T _{vi}		-40 to +150	°C
Storage Temperature	T _{stg}		-40 to +150	°C
Free-wheeling diode				
DC-Forward Current	I _F	T _c ≤ 105 °C	35	А
Non Repetitive Peak Forward Current	I _{FM}	T _c = 25 °C, t _P = 10 μs	tbd	А
Surge Non Repetitive Forward Current	I _{F.SM}	$t_p = 10 \text{ ms}$, half sine, $T_c = 25 \text{ °C}$	tbd	А

Th. Resistance Junction to Case	R _{thJC}	IGBT	0.34	K/W
Th. Resistance Junction to Case	R _{thJC}	SiC diode	0.31	K/W

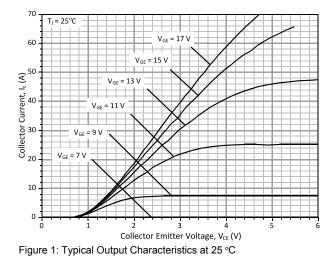
Mechanical Properties -			Values		
		min.	typ.	max.	
Mounting Torque	M _d	1.5		2	Nm

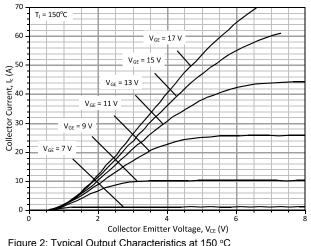
http://www.genesicsemi.com/index.php/sic-products/copack



Electrical Characteristics

Parameter	Symbol	nbol Conditions		Values		Unit
Faialletei	Symbol	Conditions	min.	typ.	max.	Unit
IGBT						
Gate Threshold Voltage	V _{GE(th)}	V _{GE} = V _{CE} , I _C = 0.6 mA, T _i = 25 °C	5.5	6	6.5	V
Callector Emitter Leekane Current	CES.25	$V_{GE} = 0 V, V_{CE} = V_{CES}, T_{I} = 25 \text{ °C}$		0.02	0.2	mA
Collector-Emitter Leakage Current	I _{CES,150}	V _{GE} = 0 V, V _{CE} = V _{CES} , T _j = 150 °C		0.3		mA
Gate-Leakage Current	I _{GES}	V _{CE} = 0 V, V _{GE} = 20 V, T _j = 25 °C			500	nA
Collector-Emitter Threshold Voltage	V _{CE(TO)}	T _j = 25°C		1.1		V
Collector-Emitter Slope Resistance	R _{CE,25}	V _{GE} = 15 V, T _j = 25 °C		50		mΩ
Collector-Emiller Slope Resistance	R _{CE,150}	V _{GE} = 15 V, T _j = 150 °C		87.5		mΩ
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	$I_{c} = 35 \text{ A}, V_{ge} = 15 \text{ V}, T_{j} = 25 \text{ °C}(150 \text{ °C})$		3.0(3.9)		V
Input Capacitance	C _{ies}			tbd		nF
Output Capacitance	C _{ee}	V_{GE} = 0 V, V_{CE} = 25 V, f = 1 MHz		tbd		nF
Reverse Transfer Capacitance	C _{res}			tbd		nF
Gate Charge	Q_{G}	V_{cc} = 800 V, I _c = 35 A, V _{gE} = 15V		50		nC
Reverse Bias Safe Operating Area	RBSOA	T _j =125 °C, R _g =56Ω, V _{cc} =1200 V, V _{GE} =15 V		45		Α
Short Circuit Current	l _{sc}	T _i = 125 °C, R _g = 56Ω,		60		Α
Short Circuit Duration	t _{sc}	V'_{cc} = 900 V, V'_{GE} = ±15 V			10	μs
Rise Time	t,			85		ns
Fall Time	t _r	V_{cc} = 800 V, I _c = 35 A,		205		ns
Turn On Delay Time	t _{d(on)}	$R_{gon} = R_{goff} = 22 \Omega,$		40		ns
Turn Off Delay Time	t _{d(off)}	$V_{GE(0n)}$ = 15 V, $V_{GE(0ff)}$ = -8 V,		232		ns
Turn-On Energy Loss Per Pulse	Eon	T _j = 125 °C		2.66		mJ
Turn-Off Energy Loss Per Pulse	E			4.35		mJ
Free-wheeling diode						
Forward Voltage	$V_{\rm F}$	$I_F = 35 \text{ A}, V_{GE} = 0 \text{ V}, T_j = 25 \text{ °C} (150 \text{ °C})$		2.6(3.5)		V
Threshold Voltage at Diode	V _{D(TO)}	T _i = 25 °C		0.8		V
Peak Reverse Recovery Current	I m			3.01		Α
Reverse Recovery Time	t _{rr}	$I_{_{\rm F}}$ = 35 A, $V_{_{ m GE}}$ = 0 V, $V_{_{ m R}}$ = 650 V		36		ns
Diode peak rate of fall of reverse recovery current during tb	dl _" /dt	$-dI_{F}/dt = 300 \text{ A/µs}, T_{j} = 125 \text{ °C}$		190		A/µs







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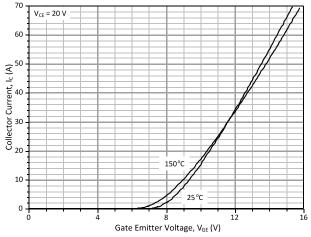
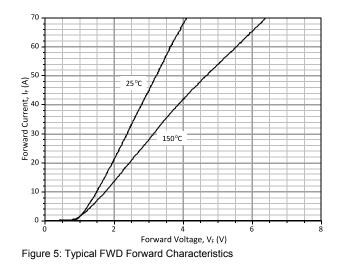


Figure 3: Typical Transfer Characteristics



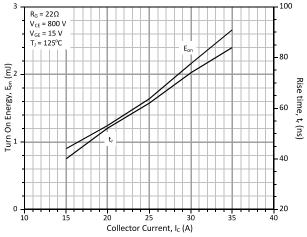


Figure 7: Typical Turn On Energy Losses and Switching Times

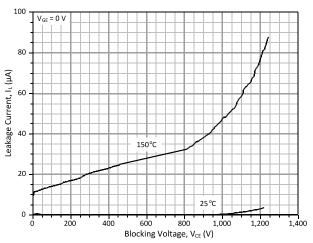


Figure 4: Typical Blocking Characteristics

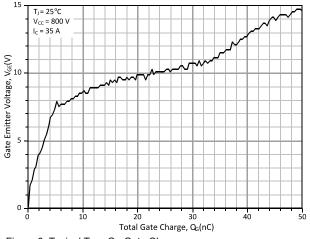


Figure 6: Typical Turn On Gate Charge

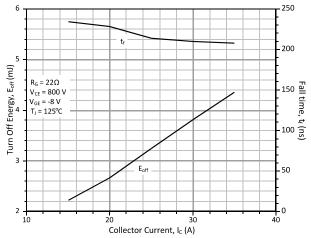


Figure 8: Typical Turn Off Energy Losses and Switching Times

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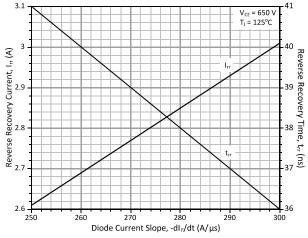
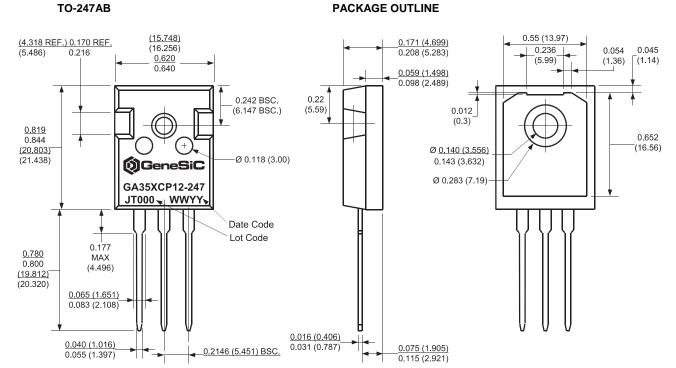


Figure 9: Typical Reverse Recovery Currents and Times

Package Dimensions:



TO-247AB

NOTE

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.

2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

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Revision History				
Date	Revision	Comments	Supersedes	
2011/01/06	1	First generation release		

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